

Multilayer Chip High Frequency Bead Array

◎ Product introduction 產品介紹

- Excellent solderability and heat resistance for either flow or reflow soldering

良好的可焊性和耐焊性

- By the use of 3-4 chip, it can be very effective in using high density circuit design of the interference suppression.

利用由3-4個芯片，它可以非常有效地採用高密度來抑制電路設計中的干擾。

- Crosstalk between adjacent circuits are minimized

回路間無串擾

- On the condition of low frequency loss is less, the impedance can be rapidly corresponding to high frequency type

在低頻下損失較少，阻抗可急速增加的高頻對應型



◎ Product application 產品應用

- Computer and peripheral equipment, DVD, camera, and other office equipment noise suppression.

電腦及周邊設備，DVD，照相機，辦公設備等雜訊抑制

◎ Product Identification 產品標識

MULT 2010 S 121 A 03 T

MULT-----Series name 系列名稱

2010-----Dimension 產品尺寸

S-----Material code 材料代碼

121-----Impedance 阻抗值【120=12Ω · 121=120Ω · 122=1200Ω】

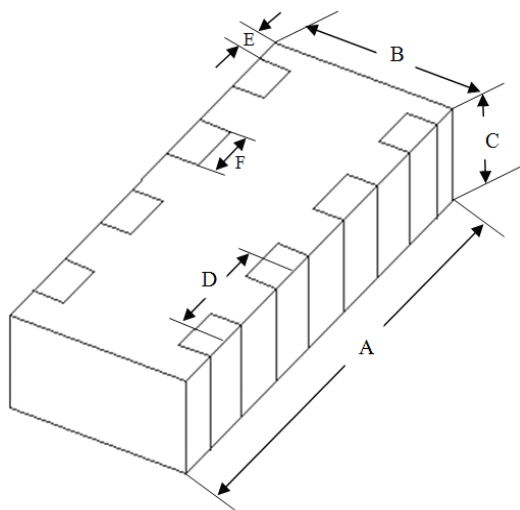
A-----High current 耐大電流

03-----Current value 電流值

T-----Taping 編帶盤裝

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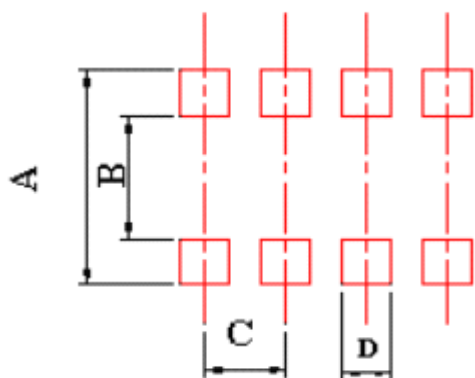
◎Shape&Dimensions 形狀與尺寸:



| SIZE CODE | A | B | C | D | E | F | CHIPS REEL |
|-----------|---------|---------|----------|---------|----------|----------|------------|
| 2010 | 2.0±0.2 | 1.0±0.2 | 0.55±0.1 | 0.5±0.1 | 0.25±0.2 | 0.25±0.2 | 4K |
| 3216 | 3.0±0.2 | 1.6±0.2 | 0.8±0.2 | 0.8±0.2 | 0.2±0.1 | 0.4±0.2 | 3K |
| | | | | | | | |
| | | | | | | | |

◎Recommender Land Pattern 推薦焊盤布局:

UNIT: mm



| SIZE CODE | A | B | C | D |
|-----------|------|------|-----|-----|
| 2010 | 1.25 | 0.25 | 0.5 | 0.3 |
| 3216 | 2.1 | 1.2 | 0.8 | 0.4 |
| | | | | |
| | | | | |
| | | | | |
| | | | | |

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◎ Detailed specifications and parameters are introduced

詳細規格及參數介紹

| ORDERING CORE | Impedance (Ω) | Test Frequency (MHz) | DC Resistance (Ω)MAX | Rated Current (mA)MAX |
|------------------|---------------------------|-------------------------|----------------------------------|--------------------------|
| MULT2010S121A03T | 120 \pm 25% | 100 | 0.300 | 300 |
| MULT2010S301A02T | 300 \pm 25% | 100 | 0.600 | 200 |
| MULT2010H260A03T | 26 \pm 25% | 100 | 0.300 | 300 |
| MULT2010H600A03T | 60 \pm 25% | 100 | 0.400 | 300 |
| MULT2010H101A02T | 100 \pm 25% | 100 | 0.550 | 200 |
| MULT2010H151A02T | 150 \pm 25% | 100 | 0.550 | 200 |
| MULT2010H221A02T | 220 \pm 25% | 100 | 0.600 | 200 |
| MULT2010H301A02T | 300 \pm 25% | 100 | 0.650 | 200 |

Standard Testing Condition:

Temperature: Ordinary Temperature(15 to 35°C), In case of doubt: 20 \pm 2°C

Humidity: Ordinary Humidity(25 to 75% RH), In case of doubt: 60 to 70 % RH

The product shall be used within 3 months of the day of manufacture.

More than this time should check the reliability of the product.

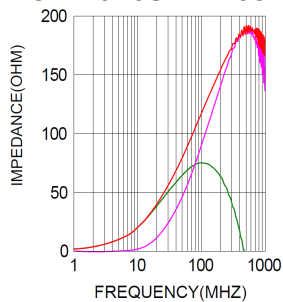
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◎ Test curve of reference as follows

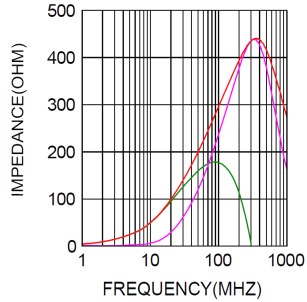
測試曲線參考如下：

— Z — R — XL

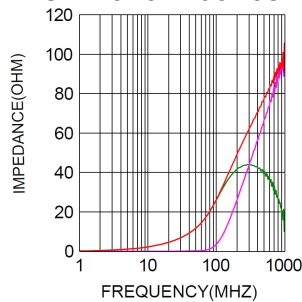
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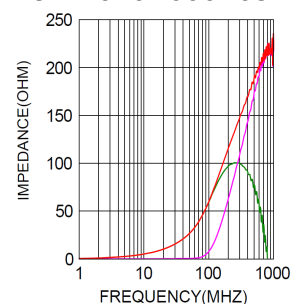
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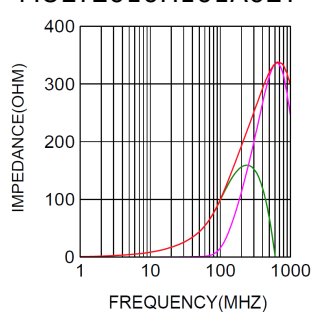
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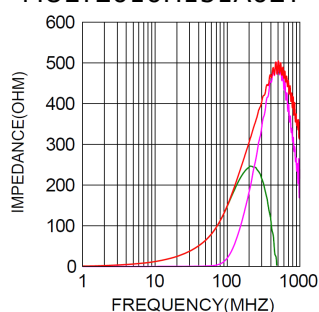
MULT2010H600A03T



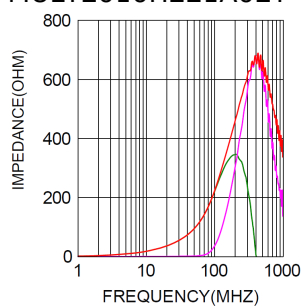
MULT2010H101A02T



MULT2010H151A02T



MULT2010H221A02T



MULT2010H301A02T

